

FIG. 1A

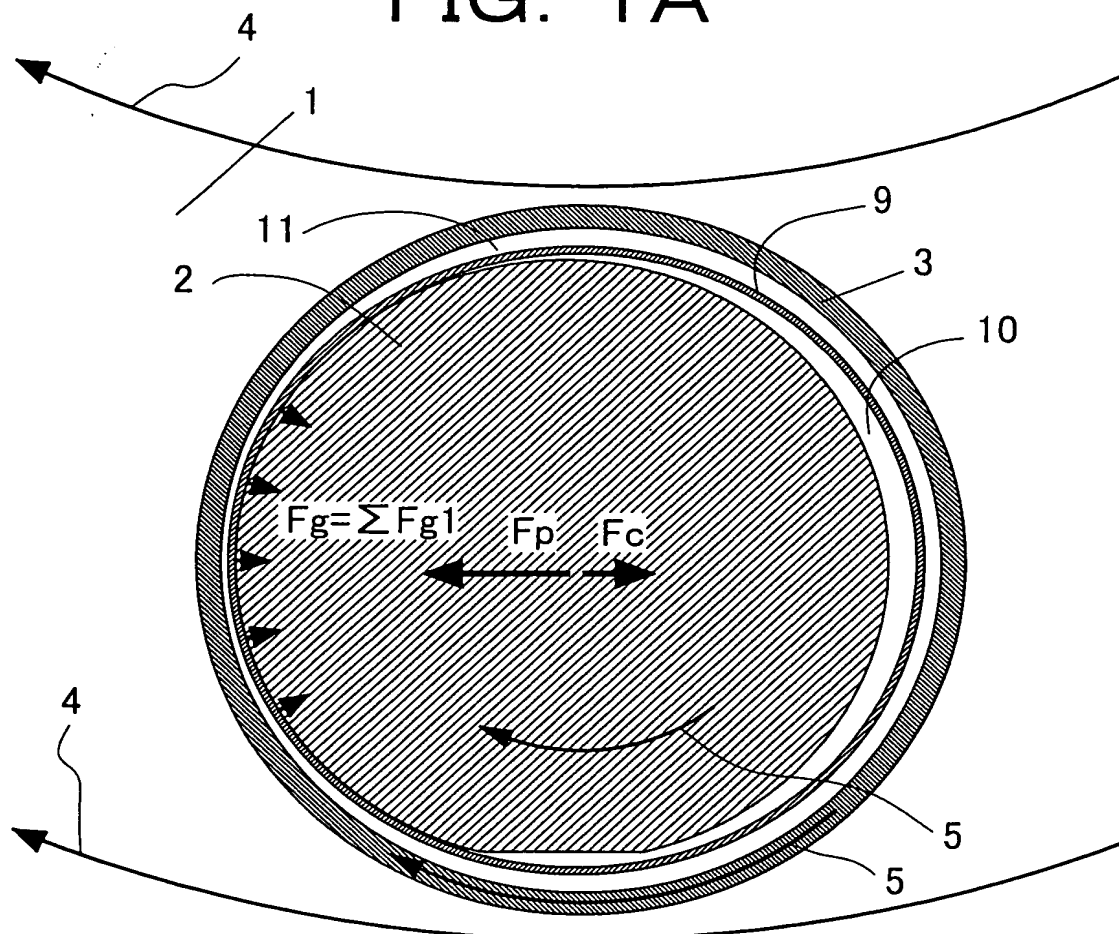


FIG. 1B

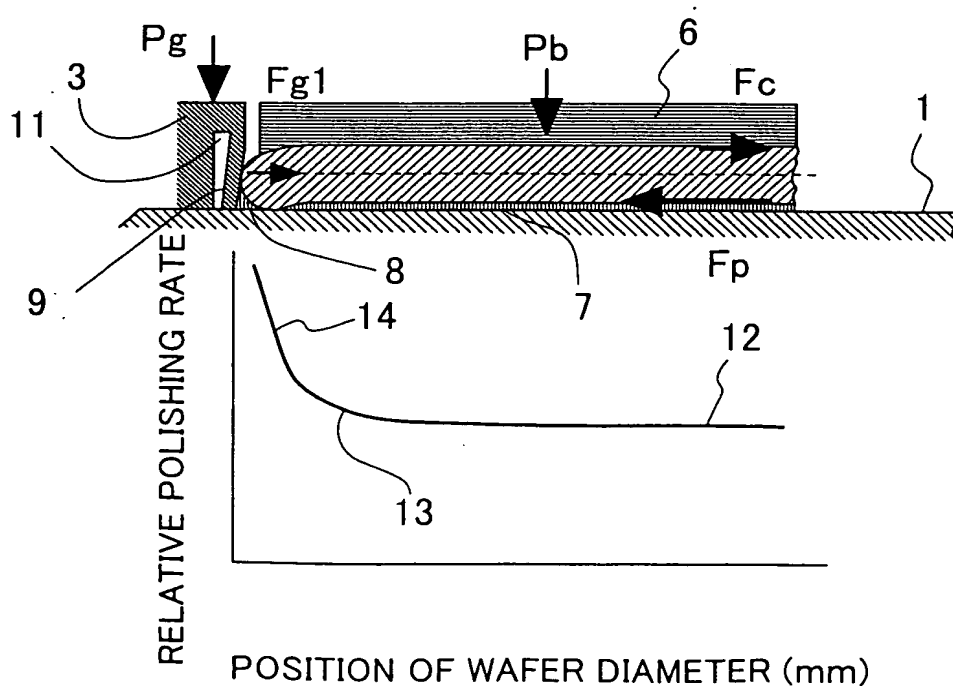


FIG. 2A

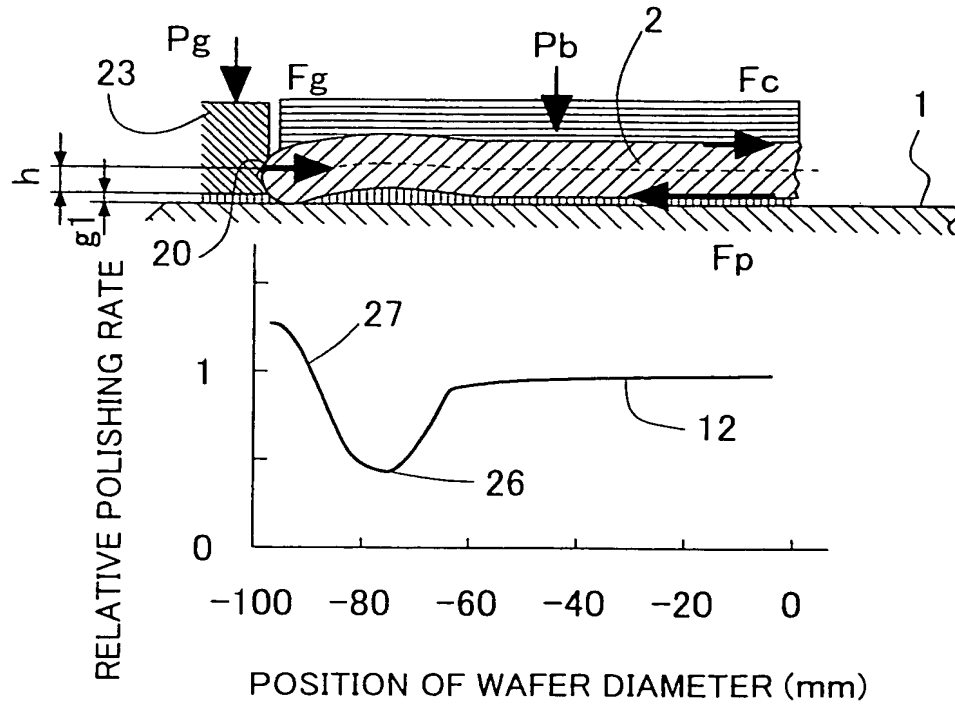


FIG. 2B

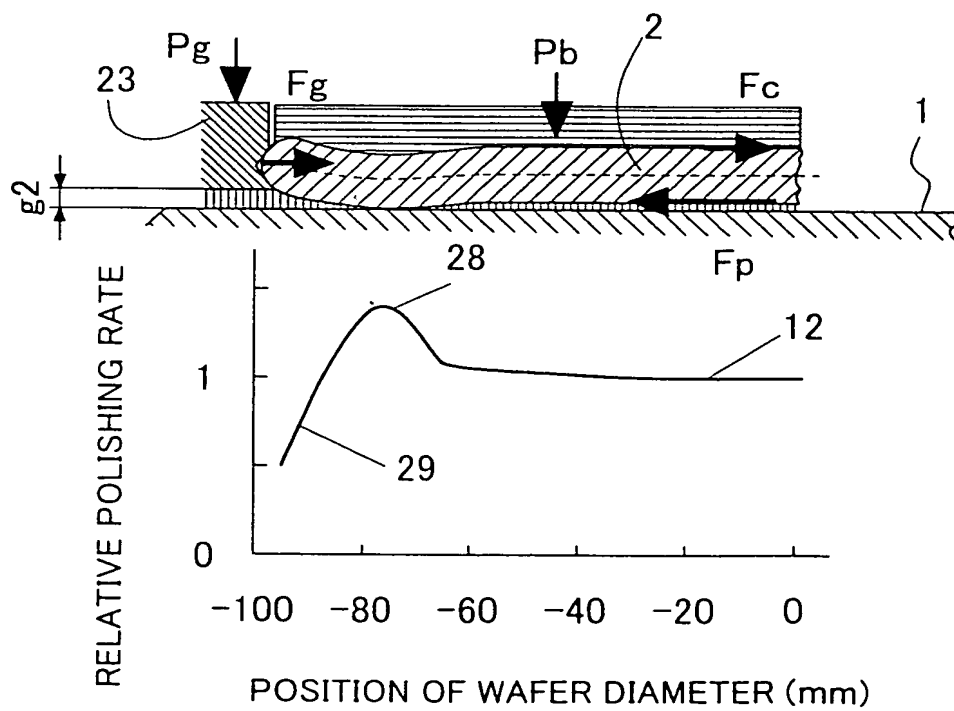


FIG. 3A

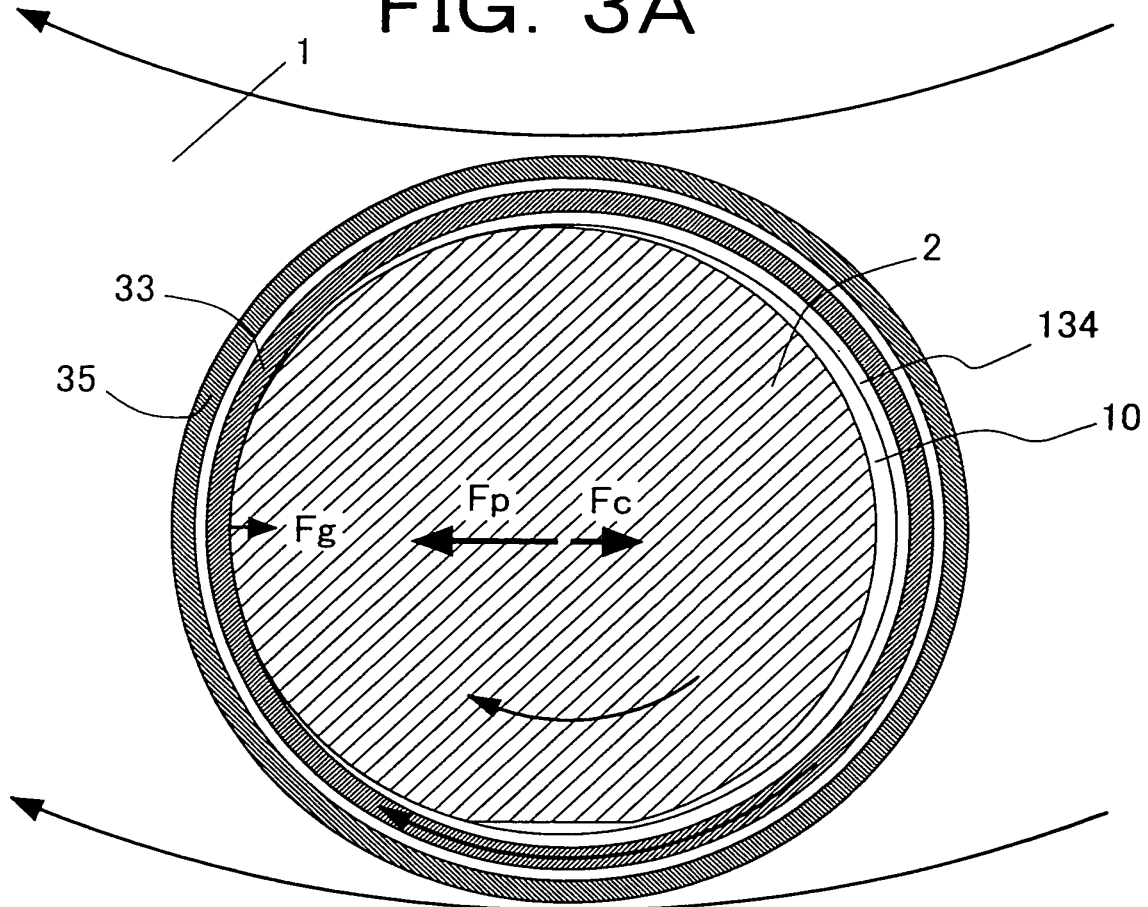
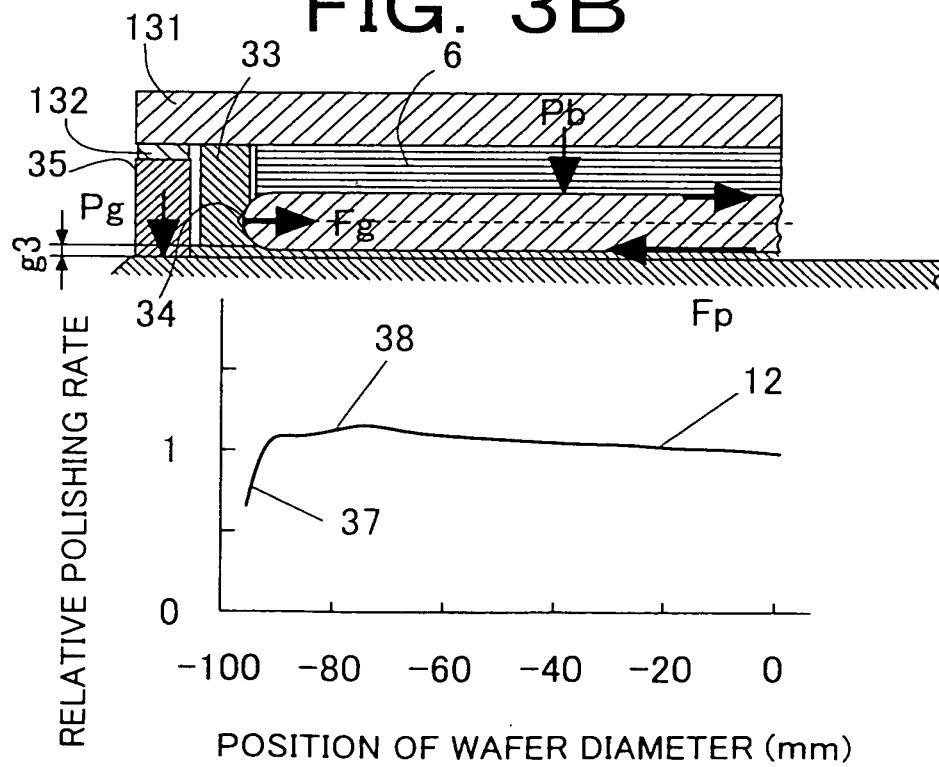


FIG. 3B



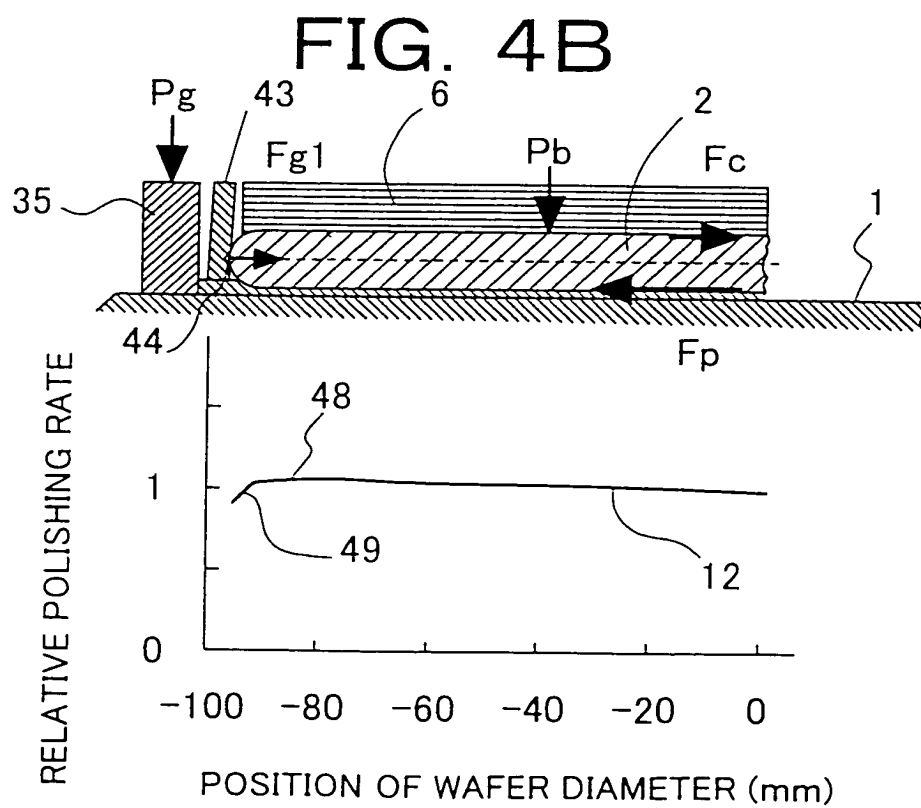
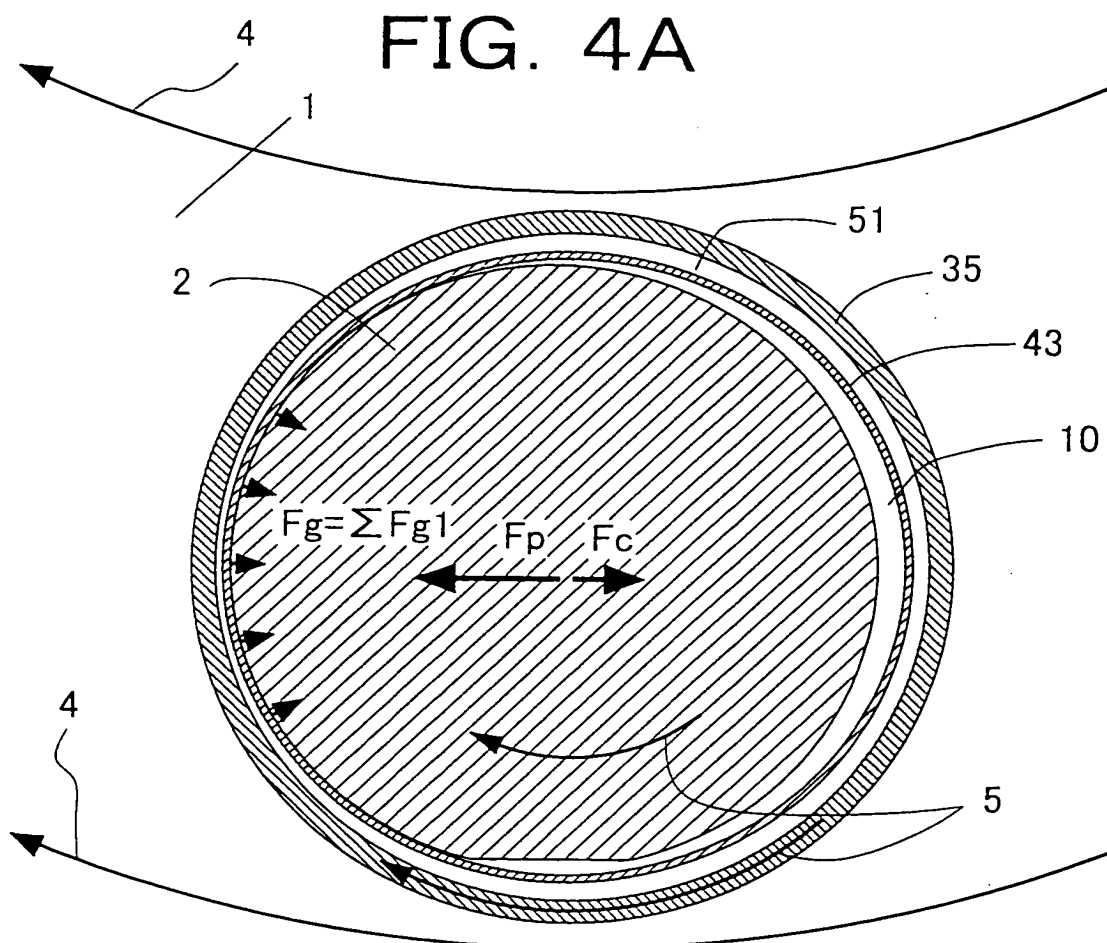


FIG. 5A

Figure 1 consists of two parts. The top part is a schematic diagram of a polishing apparatus. It shows a cross-section of a wafer (2) being polished by a polishing head (6). The head is composed of a base (35) and a polishing pad (63). A pressure P_g is applied to the pad, and a force F_g is exerted on the wafer. A pressure P_b is applied to the wafer, and a force F_c is exerted on the wafer. A force F_p is also shown. The bottom part is a graph showing the relative polishing rate (Y-axis, ranging from 0 to 1) versus the position of wafer diameter (X-axis, ranging from -100 to 0 mm). The graph shows a curve (71) that starts at a relative polishing rate of 1 at -100 mm, drops sharply to a minimum around -80 mm, and then rises back to 1. A horizontal line (12) is drawn at a relative polishing rate of 1. A label 68 points to the curve, and a label 74 points to the X-axis.

FIG. 6A

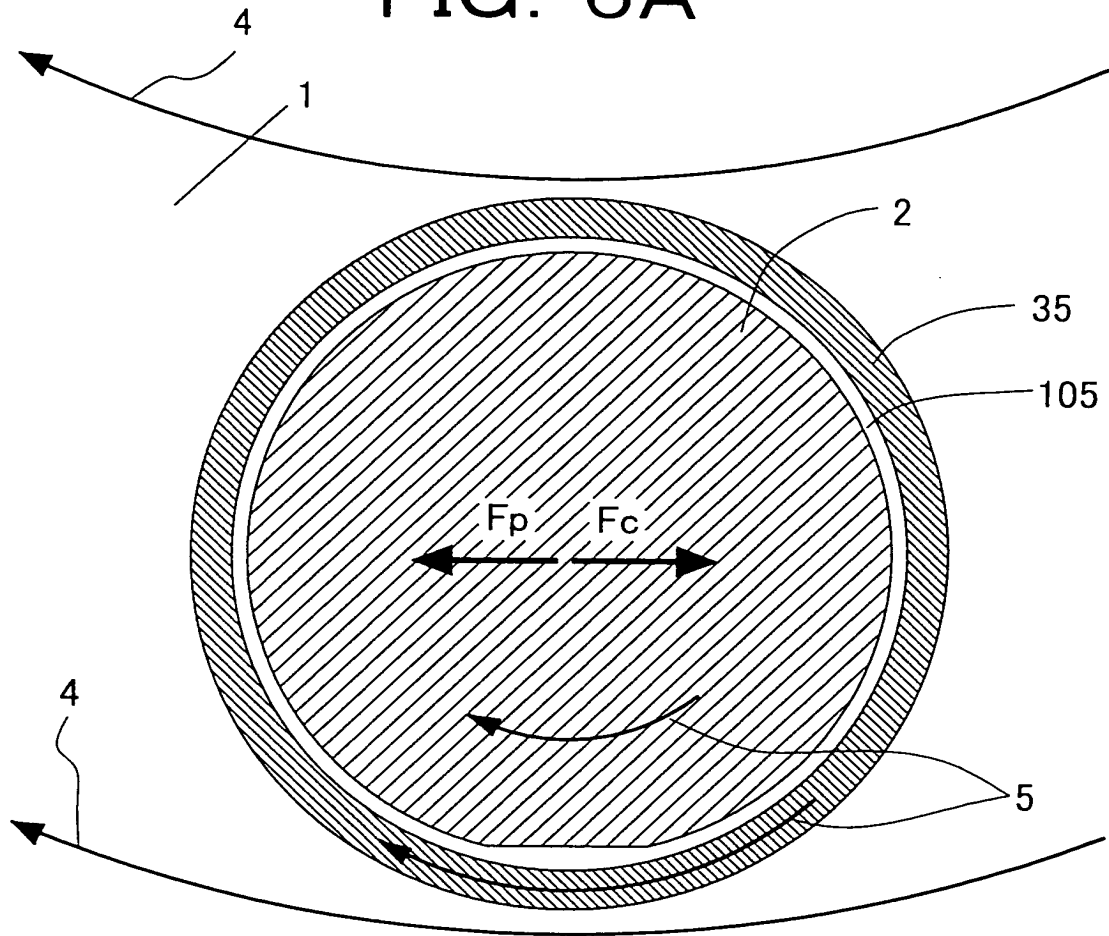


FIG. 6B

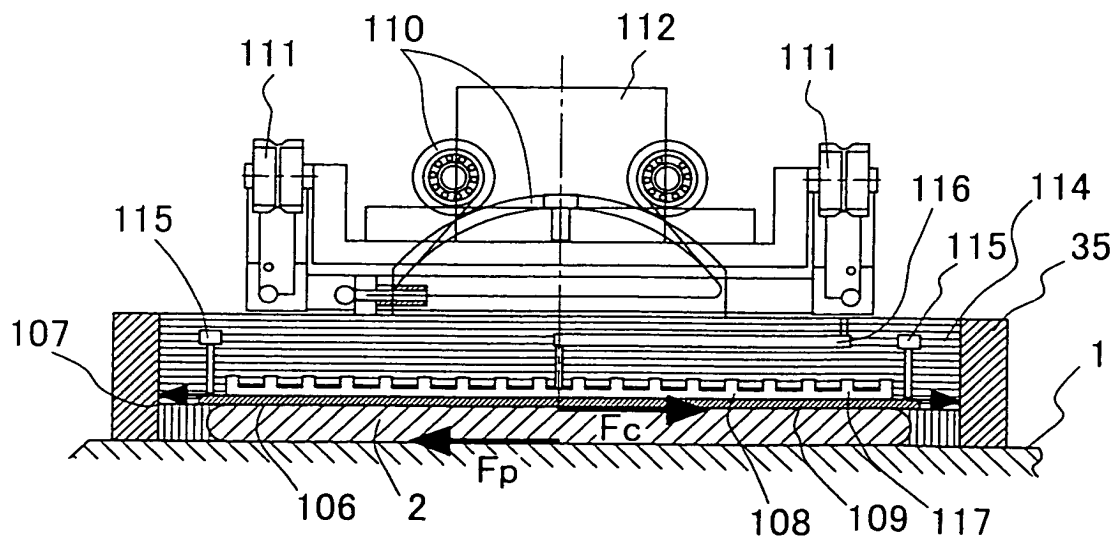


FIG. 7

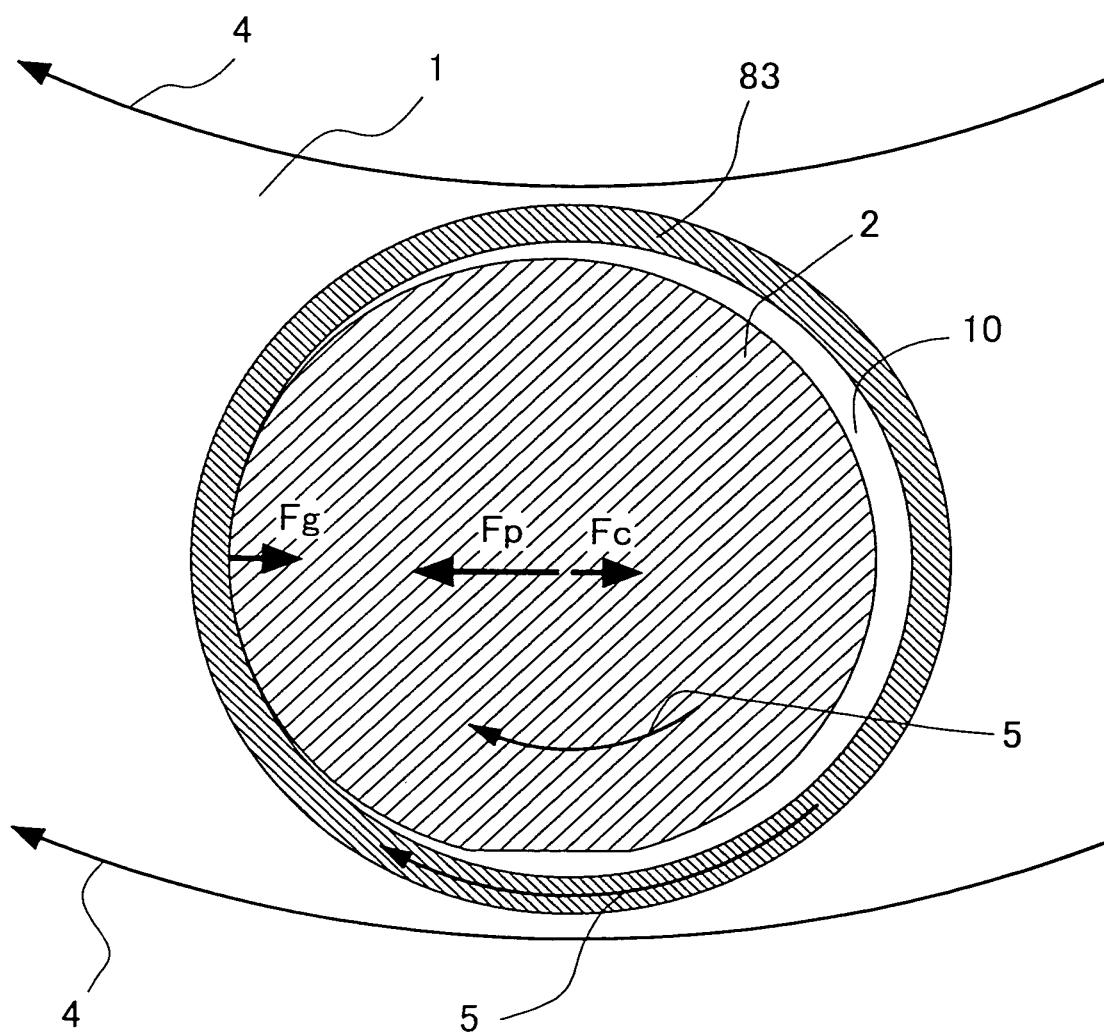


FIG. 8A

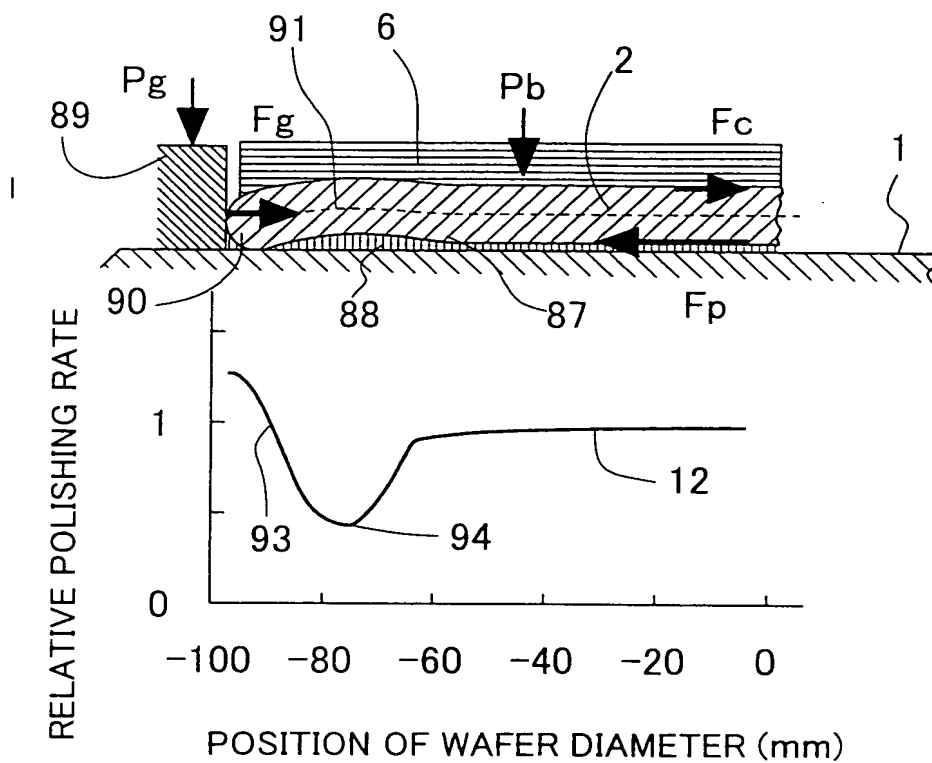


FIG. 8B

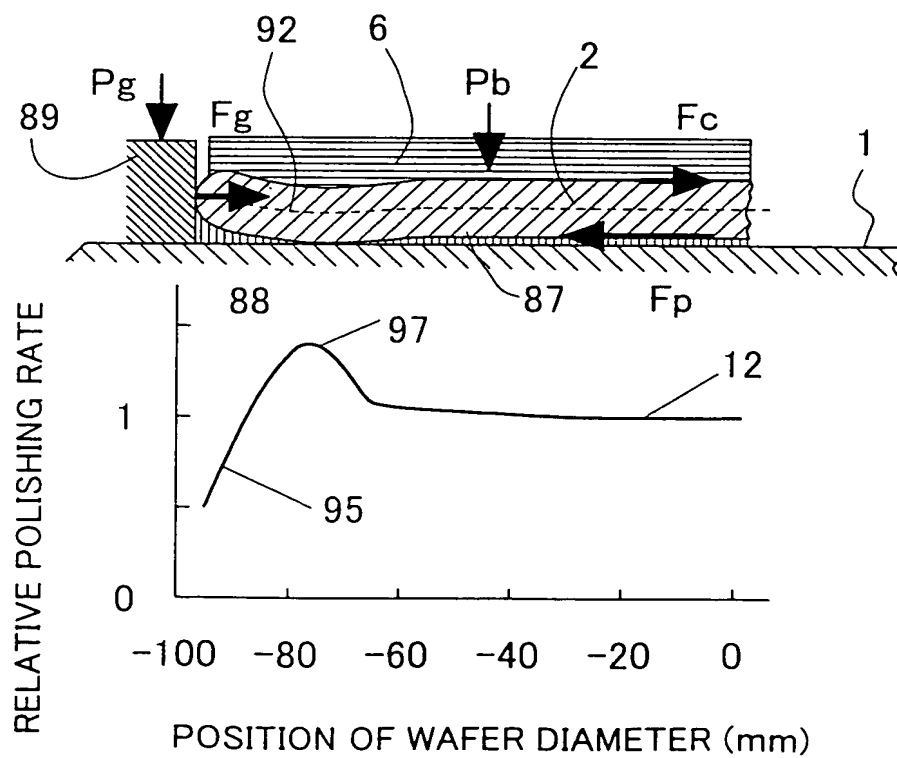


FIG. 9A

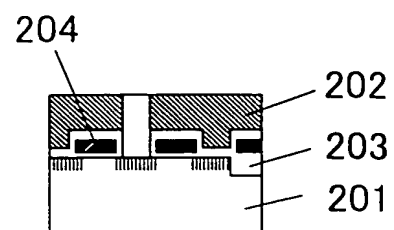
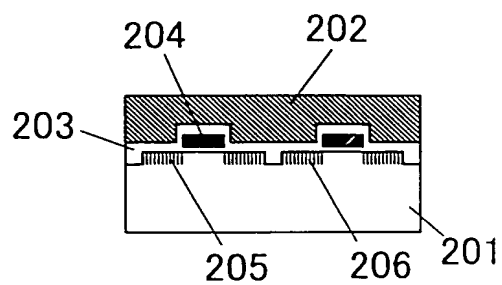


FIG. 9B

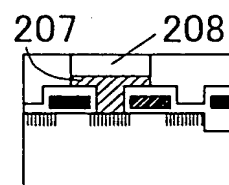
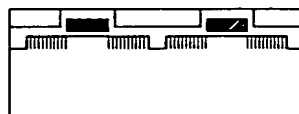


FIG. 9C

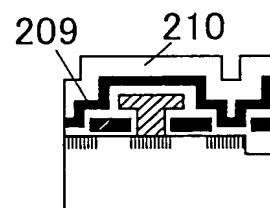
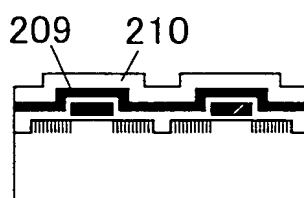


FIG. 9D

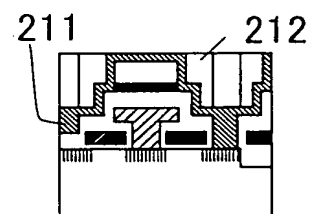
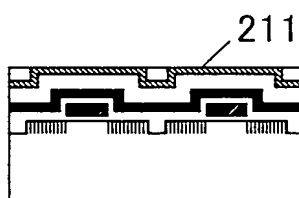


FIG. 9E

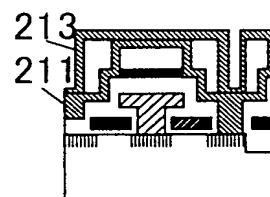
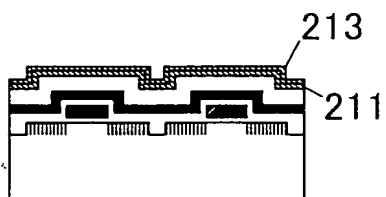


FIG. 9F

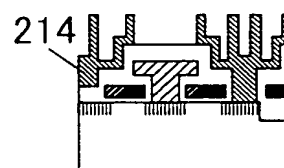
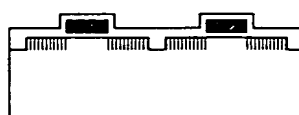


FIG. 9G

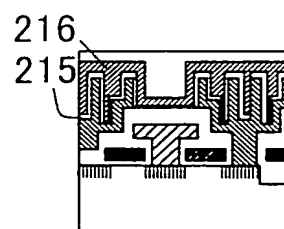
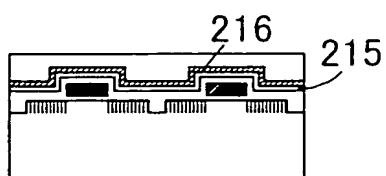


FIG. 10A

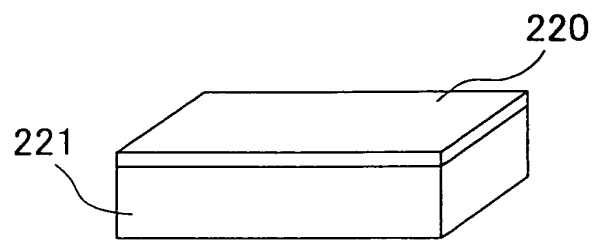


FIG. 10B

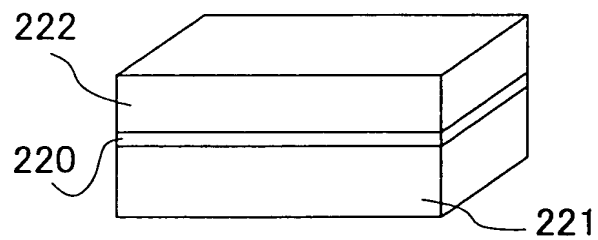


FIG. 10C

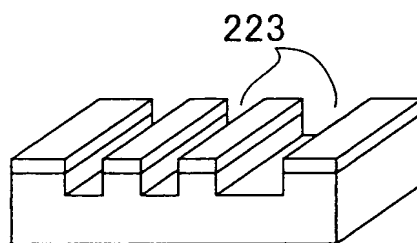


FIG. 10D

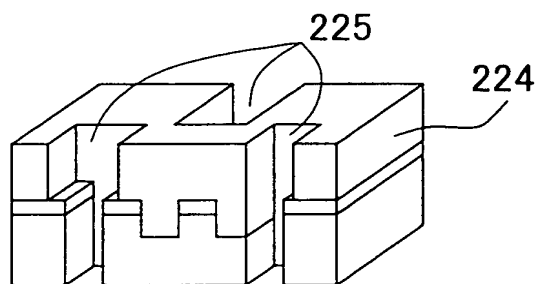


FIG. 10E

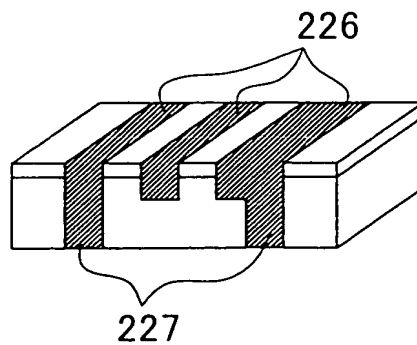


FIG. 11A

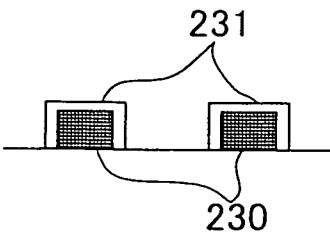


FIG. 11B

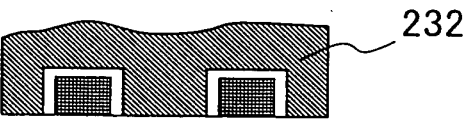


FIG. 11C

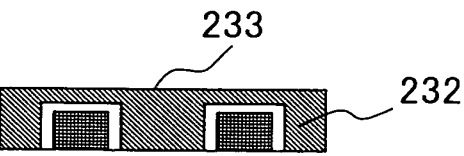


FIG. 11D

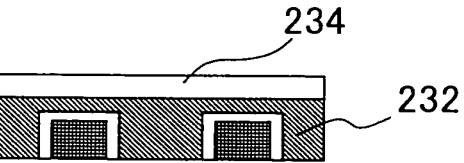


FIG. 11E

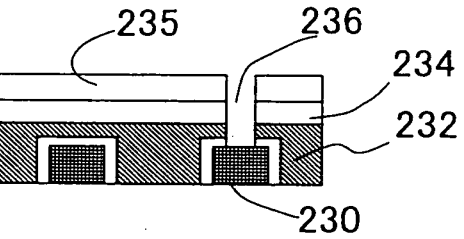


FIG. 11F

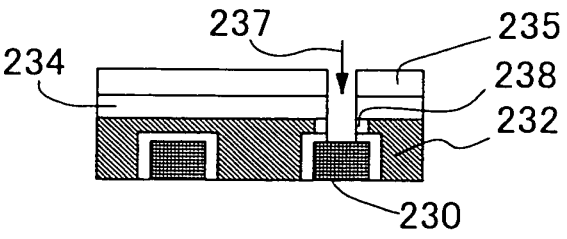


FIG. 11G

